

# Production/Technology

Major Equipment I	Name	Original	QTY	CNC Drilling machine(total 138 spindles)	Germany
10	Japan	9	China	7	5
Shenzhen	1	Scrubbing machine/Cleaning machine	Taiwan	3	12
Desmear & PTH line	Hong Kong	2	Automation plating (Gold) line	Hong Kong	1
Automation plating (Tin) line	Hong Kong	3	Automation panel plating line	Hong Kong	2
S/M Developing line	Hong Kong	2	D/F Developing line	Hong Kong	2
USA	5	Exposure machine(5KW)	Japan, Taiwan	7	2
Japan, Taiwan	7	Inner layer DES line	Taiwan, Hong Kong	2	1
Hong Kong	2	Micro-section meter	Japan	1	1
Planar test system	Taiwan	1	IR	Hong Kong	1
France	1				

Major Equipment II	Name	Original	QTY	Screening machine	Hong Kong, Taiwan	29
HAL machine	Taiwan	1	Automatic ENIG line	Hong Kong	1	
300T/200T/160T/110T/80T	Punching machine	Taiwan, China	13	CNC V-cut machine	Japan	
2	E-testing machine	Hong Kong	23	General E-testing machine	Italy	2
Flying probe tester machine	Germany	2	Vacuum Package machine	Taiwan	3	Plot
machine	Switzerland	2	OSP line	Taiwan	2	Taiwan
2	X-Ray target drilling machine	Taiwan	2	Brown Oxide line	Hong Kong	1
Conveyor Oven	Hong Kong	3	TDR Characteristic impedance machine	special process to be		
handed outside of our facilities	1	Automatic Laminate machine	Japan	2	Output capacity	
PCB	Monthly Output	2005	2006	2007	Double side	25,000m2
35,000m2	Multi-layer	15,000m2	30,000m2	35,000m2	Total	40,000m2
70,000m2	Flexible PCB	Monthly Output	2005	2006	2007	60,000m2
10,000m2	800m2	12,000m2	Double Side & Multi-layer	5,000m2	10,000m2	12,000m2
Total	15,000m2	18,000m2	24,000m2			

Production Capacity Layer Counts: 1-14 Material: FR-4, High TG FR-4, PTFE, Aluminum Base, Rogers. Maximum Size: 500mmX600mm Board Outline Tolerance: ±0.13 mm Board Thickness: 0.20mm&mdash;6.00mm Thickness Tolerance (t=0.8mm): ±8% Thickness Tolerance (t<0.8mm): ±10% Insulation Layer Thickness: 0.075mm&mdash;5.00mm Minimum Line: 0.2mm Minimum Space: 0.2mm Out-layer Copper Thickness: 35µm&mdash;175µm In-layer Copper Thickness: 17µm-175µm Drilling Hole (Mechanical): 0.15mm&mdash;6.35mm Finish Hole (Mechanical): 0.15mm&mdash;6.30mm Diameter Tolerance (Mechanical): 0.05mm Registration (Mechanical): 0.075mm Aspect Ratio: 8:1 Solder Mask Type: Ink SMT Mini. Solder Mask Width: 0.08mm Mini Solder Mask Clearance: 0.05mm Plug Hole Diameter: 0.25mm&mdash;0.60mm Impedance Control Tolerance: ±10% Surface Finish: HASL, ENIG, Chem, Tin, Flash Gold, OSP, Gold finger 2. Application : Telecommunication, Network, Industrial control, Medical equipment, PC& periphery 3. 1) Characteristic: 0.5mm CSP Blind & Buried Hole Application : Blue tooth 2) Characteristic: up to 12 layer, Tg170 0.8mm BGA ±10% Impedance control Application: Telecommunication, Network, Medical equipment, etc 3) Characteristic: Al-Base Application: Power supply, Power Amplifier, relay, LED,etc 4) Characteristic: Up to 16 layer, Blind & Buried hole Heavy copper 950z), Up to 6.0 mm board thickness Application: Secondary Power source Fast delivery time for prototypes (in normal working conditions):

Category	Quickest lead time	Normal lead time	Double side	2/3 days
4 days				
4 layers	4/5 days			
5/6 days				
6 layers	4/5 days	5/6 days	8 layers	6/7 days
7/8 days				
10 layers	6/7 days	7/8 days		
12 layers	8/9 days			
9/10 days				
14 layers	8/9 days			
9/10 days				

